

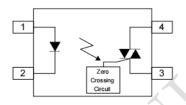
Photo Coupler Product Specification

HTM-304X_306X_308X



■ Package





Pin Configuration

- 1 Anode
- 2 Cathode
- 3 Terminal
- 4 Terminal

Description

The HTM-304X_306X_308X series devices are optocouplers composed of a GaAs infrared light emitting diode and a single-crystal silicon chip Zero-cross photoelectric bidirectional thyristor.

■ Features

Peak breakdown voltage

HTM-304X: Min.400V

HTM-306X: Min.600V

HTM-308X: Min.800V

- 4pin zero-cross optoisolators triac driver outp
- High input-output isolation voltage(Viso = 3,750Vrms)
- Operating Temperature: -40 ℃~110 ℃
- Safety approval

UL approved

VDE approved

CQC approved

- RoHS
- MSL1

■ Applications

- Lighting Control
- AC Motor Starter
- Static power switc
- Temperature Controls



■ Product Nomenclature

The product name is designated as below:

<u>HT M-30XX -X X X-XX</u>

1 2 3 4

Designation:

HT =Hengtuo Technology Co.,LTD.

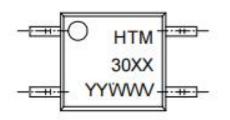
M= Packaging form

30XX=Product series(304X/306X/308X, X:1/2/3)

- ① = Tape and Reel option(TP,TP1,NONE)
- ② = VDE order option(fixed code "V")
- ③ = Halogen free option(fixed code"G")
- ④ = Customer code



■ Marking Information



■ Maximum

Designation:

HT denotes Hengtuo
M Packaging form
30XX denotes Device
YY denotes year code
WW denotes week code

V denotes VDE

Parameter			Symbol	Values	Unit
	Forward Current		I _F	50	mA
loout	Reverse Voltage		V _R	6	V
Input	Power Dissipation		P	120	MW
	Junction Temperature		T_{J}	100	$^{\circ}$
	Off Chaha Outrout	HTM-304X		400	V
	Off-State Output Terminal Voltage	HTM-306X	V_{DRM}	600	
		HTM-308X		800	
Output	On state RMS current		I _{T(RMS)}	100	mA(RMS)
Output	Peak Repetitive Surge Current (PW=1ms, 120 pps		I _{TSM}	1	А
	Junction Temperature		T_J	125	${\mathbb C}$
	Collector Power Dissipation		Pc	300	mW
Operati	ng temperature ran	ge	T _{op}	- 40 ~ 110	° C
Storage temperature range			T_{stg}	− 55 ~ 125	° C
Total Power consumption			P _(W)	330	mW
Isolation Voltage ⁽¹⁾			V _{ISO}	5000	Vrms
Soldering Temperature ⁽²⁾			T _{SOL}	260	° C

Notes:

^{(1).} AC for 1 minute, R.H.= $40 \sim 60\%$ R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

^{(2).}For 10 seconds



■ Electronic Optical Characteristics

 $(TA = 25^{\circ}C)$

	Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditon
Input	Forward Voltage	V _F	-	1.2	1.6	V	I _F =10mA
	Reverse Current	I _R	-	-	5	μA	V _R =6V
Output	Peak Blocking Current, Either Directiot (1)	I _{DRM}	-	10	100	nA	V _{DRM} = Rated V _{DRM}
	Inhibit Voltage (MT1-MT2 voltage above which device will not trigger)	V _{INH}	-		20) -	I _F = Rated I _F
	Peak On-State Voltage, Either Dire	V _{TM}	\-_\	-)	3	V	I _™ =100mA Peak
	Critical rate of Rise of Off-State Voltage (2)	dv/dt	1000	-	-	V / μ s	V _{in} =240Vrms
	Led HTM-3041 Trigger HTM-3061 Current,Cu HTM-3081		-	-	15		
	rrent HTM-3041 Required HTM-3062 to Latch HTM-3082	I _{FT}	-	-	10	mA	Main Terminal Voltage = 3V
	Output, HTM-3041 Either HTM-3063 Direction HTM-3083		-	-	5		
	Holding Current, Either Direction	Ін	-	280	-	uA	
ZERO CROSSI NG	Leakage in Inhibited State	I _{DRM2}	-	-	500	uA	I _F = Rated I _{FT} , Rated V _{DRM} , Off State

⁽¹⁾ Test voltage must be applied within dv/dt rating.

⁽²⁾ This is static dv/dt. Commutating dv/dt is a function of the load-driving thyristor(s) only.



■ Characteristics Curves

Fig.1 Forward current vs Ambient temperature

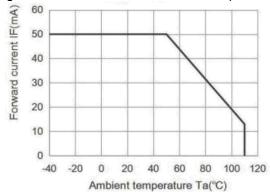


Fig.3 Minimun Trigger Current vs.Ambient temperature

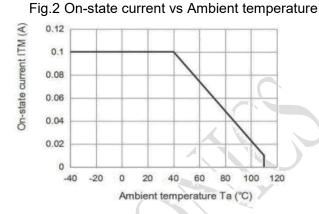


Fig.4 Forward current vs Forward Voltage

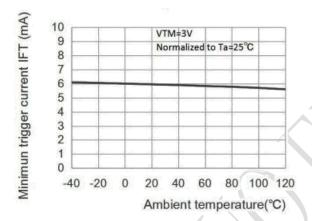
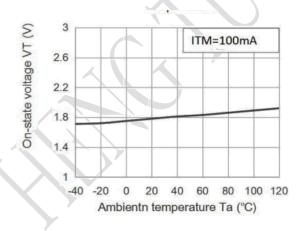


Fig.5 On-state voltage vs Ambient temperature



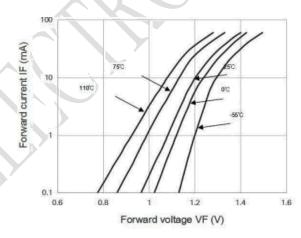


Fig.6 Holding current vs Ambient temperature

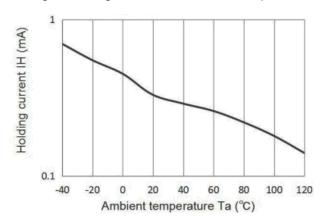




Fig.7 Repetitive peak off-state current vs Temperature

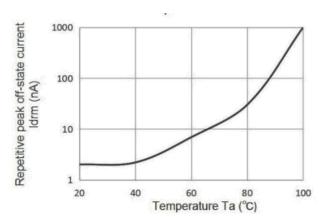


Fig.8 On-state current vs On-state voltage

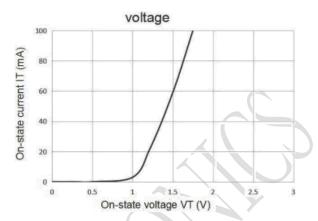


Fig.9 Basic Operation Circuit Medium/High Power Triac Drive Circuit

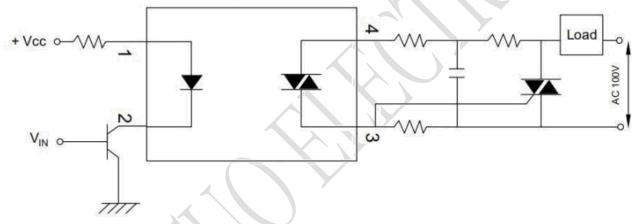
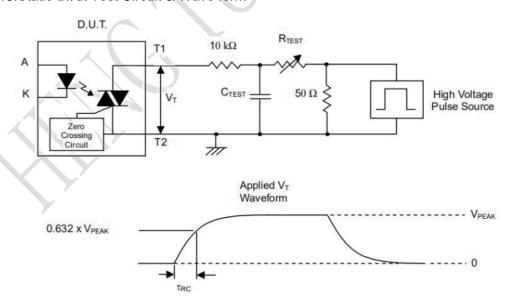
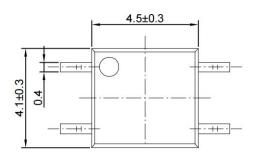


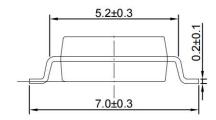
Fig10.Static dv/dt Test Circuit & Wave form

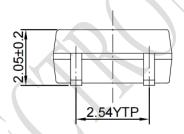




■ Outline Dimension



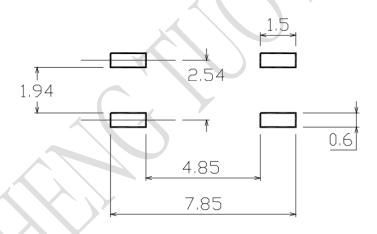




Unit: mm

Tolerance: ±0.1mm

■ Recommended solder pad Design



Unit: mm

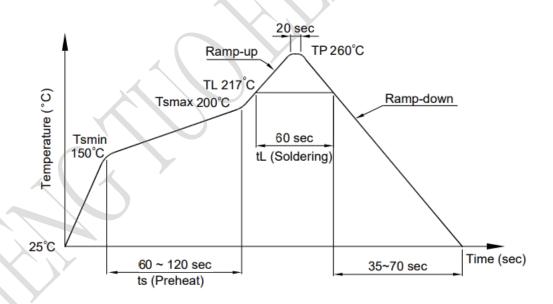
Tolerance: ±0.1mm



■ Temperature Profile Of Soldering

1. IR Reflow soldering (JEDEC-STD-020 compliant)

Profile item	Conditon
Preheat -Temperature Min (TSmin) -Temperature Max (TSmax) -Time (min to max) (ts)	150°C 200°C 90±30 sec
Soldering zone -Temperature (TL) -Time (tL)	217°C 60 sec
Peak Temperature (TP)	260°C
Ramp-up rate	3°C / sec max
Ramp-down rate	3~6°C/ sec

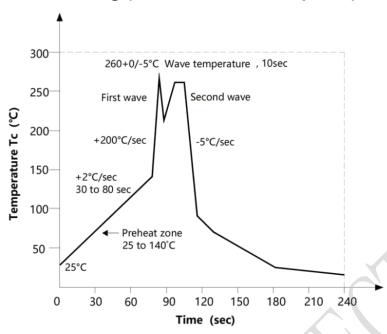


Notes:

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.



2. Wave soldering (JEDEC22A111 compliant)



3. Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

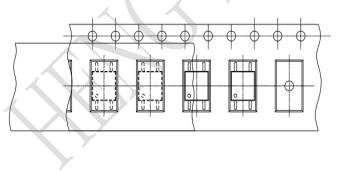
Temperature: 380+0/-5°C

Time: 3 sec max.

■ Packing

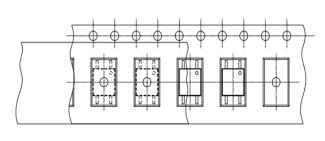
Tape and Reel

Option TP:



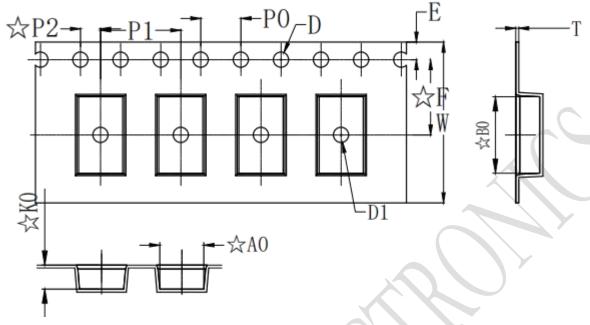


Option TP1:









Deminsion/mm	W	E	F	P0	P1	P2
Packagetype:S	16±0.2	1.75±0.1	7.5±0.1	4±0.1	8±0.1	2±0.1

Deminsion/mm	A0	В0	D0	D1	K0
Packagetype:S	4.4±0.1	7.6±0.1	1.5±0.1	1.5±0.1	2.4±0.1

Packagetype:S	Reel	Inner carton	Outer carton
QTY/PCS	1K/reel	2K(2 reels)	20K



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- When requiring a device for any "specific" application, please contact our sales in advice.
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